PRODUCT CHANGE NOTICE					
PART NUMBER(S):	PCN No.: 06-0130-13a				
Please see attachment.	DATE: June 23, 2006				
PART DESCRIPTION:					
Power Management and Interface Products – Change in Wafer Fabrication Site					
LEVEL OF CHANGE:					
[X] Level I, Customer Approval.	[] Level II, Customer Information.				
PRODUCT ATTRIBUTE AFFECTED:					
[] Material Change] Data Sheet Change				
[] Design Change [[X] Process Change [Package ChangePacking / Shipping				
[X] Other, Explain: Wafer Fabrication Site Transfer					
DESCRIPTION OF CHANGE:					
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry EPISIL. See attached Product List no. 13.					
REASON FOR CHANGE:					
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.					

FABRICATION PROCESS QUALIFICATION

COMPLETED (DATE): November 22, 2006

-Solved by

PRODUCT CHARACTERIZATION COMPLETED AND

SAMPLES* AVAILABLE (DATE): November 29, 2006

^{*} Samples representative of product from the Product Family being transferred.



	PRODUCT CHANGE NOTICE				
EARLIEST DATE OF PRODUCTION SHIPMENTS: January 31, 2007					
EFFECTIVITY CHANGE DATE OR DA	ATE CODE: Work	week associated wit	h earliest production shipment.		
[] STANDARD DISTRIBUTION		[X]	CUSTOM DISTRIBUTION		
PERSON TO CONTACT WITH QUES	TIONS:				
Fred Claussen					
VP Quality Assurance and Reliability Sipex Corporation Phone Number: 408-935-7644 FAX NUMBER: 408-935-7678					



PRODUCT CHANGE NOTICE

PCN No.: 06-0130-13

List 13

SP485RCN

SP485RCN-L

SP485RCP

SP485RCP-L

SP485RCS-L

SP485REN

SP485REN-L

SP485REP

SP485REP-L

SP485RES-L